

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently amended) A plasma processing apparatus comprising:
 - a vacuum chamber accommodating therein a substrate to be processed, allowing an inner space of the vacuum chamber to be maintained at a vacuum level;
 - a first electrode fixedly disposed at a location in the vacuum chamber;
 - a second electrode installed in the vacuum chamber and facing the first electrode, the second electrode being vertically movable so as to vary a distance between the first electrode and the second electrode;
 - a driving mechanism for vertically moving the second electrode, the driving mechanism being installed outside the vacuum chamber;
 - a bellows unit for airtightly sealing an opening, the bellows unit having an upper bellows portion, a lower bellows portion, and a ring member connected to the driving mechanism, wherein the opening, through which the second electrode is driven by the driving mechanism from the outside of the vacuum chamber via the ring member, is provided at the vacuum chamber, and the ring member is disposed between the upper bellows portion and the lower bellows portion;
 - an electrode supporting member for supporting the second electrode and connecting the ring member to the second electrode, the electrode supporting member being installed in the vacuum chamber; and
 - a high frequency power source generating plasma by supplying a high frequency power between the first electrode and the second electrode,

wherein the upper bellows portion and the lower bellows portion are oppositely extended and contracted in accordance with a vertical movement of the ring member while maintaining a constant total length of the bellows unit.

2. (Original) The plasma processing apparatus of claim 1, wherein the first electrode and the second electrode are a lower electrode and an upper electrode, respectively.

3. (Original) The plasma processing apparatus of claim 2, wherein the upper electrode is supported from underneath the lower electrode.

4. (Original) The plasma processing apparatus of claim 3, wherein the electrode supporting member includes an exhaust ring for uniformly exhausting the vacuum chamber.

5. (Original) The plasma processing apparatus of claim 3, wherein the electrode supporting member includes a cylindrical member for protecting an inner wall of the vacuum chamber.

6. (Original) The plasma processing apparatus of claim 3, further comprising a substrate supporting member for supporting the substrate to be processed above the lower electrode, the substrate supporting member being vertically movable by the driving mechanism to pass through the lower electrode.

7. (Previously presented) The plasma processing apparatus of claim 2, wherein the distance between the first electrode and the second electrode is varied while constantly maintaining a volume of the vacuum chamber maintained in vacuum.

8. (Canceled)

9. (Currently amended) A vacuum processing apparatus comprising:
a vacuum chamber accommodating therein a substrate to be processed, allowing an

inner space of the vacuum chamber to be maintained at a vacuum level;

a first structure fixedly disposed at a location in the vacuum chamber;

a second structure installed in the vacuum chamber and facing the first structure, the second structure being vertically movable so as to vary a distance between the first structure and the second structure;

a driving mechanism for vertically moving the second structure, the driving mechanism being installed outside the vacuum chamber;

a bellows unit for airtightly sealing an opening, the bellows unit having an upper bellows portion, a lower bellows portion, and a ring member connected to the driving mechanism, wherein the opening, through which the second structure is driven by the driving mechanism ~~from the outside of the vacuum chamber via the ring member~~, is provided at the vacuum chamber, and the ring member is disposed between the upper bellows portion and the lower bellows portion; and

a structure supporting member for supporting the second structure and connecting the ring member to the second structure, the structure supporting member being installed in the vacuum chamber,

wherein the upper bellows portion and the lower bellows portion are oppositely extended and contracted in accordance with a vertical movement of the ring member while maintaining a constant total length of the bellows unit.

10. (Previously presented) The vacuum processing apparatus of claim 9, wherein the first structure and the second structure are a lower electrode and an upper electrode, respectively.

11. (Previously presented) The vacuum processing apparatus of claim 10, wherein the upper electrode is supported from underneath the lower electrode.

12. (Previously presented) The vacuum processing apparatus of claim 11, wherein the structure supporting member includes an exhaust ring for uniformly exhausting the vacuum chamber.

13. (Previously presented) The vacuum processing apparatus of claim 11, wherein the structure supporting member includes a cylindrical member for protecting an inner wall of the vacuum chamber.

14. (Previously presented) The vacuum processing apparatus of claim 11, further comprising a substrate supporting member for supporting the substrate to be processed above the lower electrode, the substrate supporting member being vertically movable by the driving mechanism to pass through the lower electrode.

15. (Previously presented) The vacuum processing apparatus of claim 10, wherein the distance between the first electrode and the second electrode is varied while constantly maintaining a volume of the vacuum chamber maintained in vacuum.

16. (Canceled)